



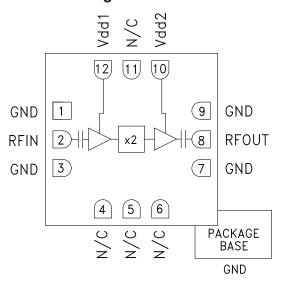
SMT GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 18 - 29 GHz OUTPUT

Typical Applications

The HMC576LC3B is suitable for:

- Clock Generation Applications:
 SONET OC-192 & SDH STM-64
- Point-to-Point & VSAT Radios
- Test Instrumentation
- Military & Space

Functional Diagram



Features

High Output Power: +15 dBm

Low Input Power Drive: 0 to +6 dBm
Fo Isolation: >20 dBc @ Fout= 24 GHz
100 KHz SSB Phase Noise: -132 dBc/Hz

Single Supply: +5V@ 82 mA

RoHS Compliant 3x3 mm SMT Package

General Description

The HMC576LC3B is a x2 active broadband frequency multiplier utilizing GaAs PHEMT technology in a leadless RoHS compliant SMT package. When driven by a +3 dBm signal, the multiplier provides +15 dBm typical output power from 18 to 29 GHz. The Fo and 3Fo isolations are >20 dBc at 24 GHz. The HMC576LC3B is ideal for use in LO multiplier chains for Pt-to-Pt & VSAT Radios yielding reduced parts count vs. traditional approaches. The low additive SSB Phase Noise of -132 dBc/Hz at 100 kHz offset helps maintain good system noise performance. The RoHS packaged HMC576LC3B eliminates the need for wire bonding, and allows the use of surface mount manufacturing techniques.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vdd1, Vdd2 = +5V, 3 dBm Drive Level

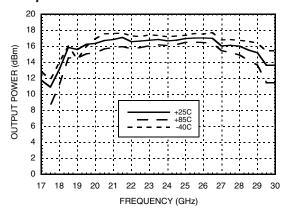
| Parameter | Min. | Тур. | Max. | Units |
|--|------|----------|------|--------|
| Frequency Range, Input | | 9 - 14.5 | | GHz |
| Frequency Range, Output | | 18 - 29 | | GHz |
| Output Power | 10 | 15 | | dBm |
| Fo Isolation (with respect to output level) | | 20 | | dBc |
| 3Fo Isolation (with respect to output level) | | 20 | | dBc |
| Input Return Loss | | 10 | | dB |
| Output Return Loss | | 10 | | dB |
| SSB Phase Noise (100 kHz Offset) | | -132 | | dBc/Hz |
| Supply Current (Idd1 & Idd2) | | 82 | | mA |



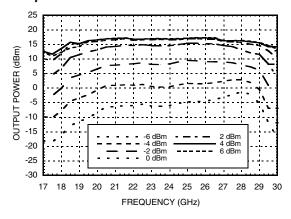


SMT GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 18 - 29 GHz OUTPUT

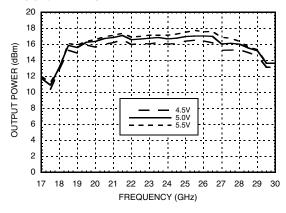
Output Power vs. Temperature @ 3 dBm Drive Level



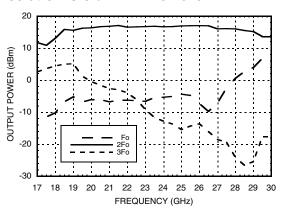
Output Power vs. Drive Level



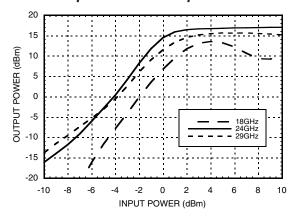
Output Power vs. Supply Voltage @ 3 dBm Drive Level



Isolation @ 3 dBm Drive Level



Output Power vs. Input Power

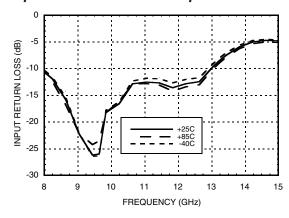




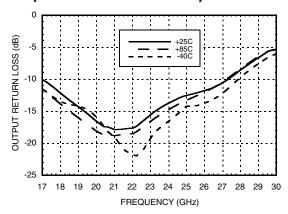


SMT GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 18 - 29 GHz OUTPUT

Input Return Loss vs. Temperature



Output Return Loss vs. Temperature







SMT GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 18 - 29 GHz OUTPUT

Absolute Maximum Ratings

| RF Input (Vdd = +5V) | +13 dBm |
|---|----------------|
| Supply Voltage (Vdd) | +6.0 Vdc |
| Channel Temperature | 175 °C |
| Continuous Pdiss (T= 85 °C) (derate 7.5 mW/°C above 85 °C) | 676 mW |
| Thermal Resistance (channel to ground paddle) | 133 °C/W |
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -40 to +85 °C |

Typical Supply Current vs. Vdd

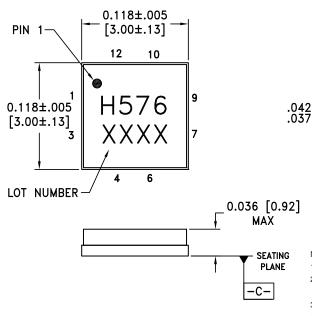
| Vdd (Vdc) | Idd (mA) | | |
|-----------|----------|--|--|
| 4.5 | 82 | | |
| 5.0 | 82 | | |
| 5.5 | 83 | | |

Note

Multiplier will operate over full voltage range shown above.



Outline Drawing



NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [2] |
|-------------|-----------------------|------------------|------------|---------------------|
| HMC576LC3B | Alumina, White | Gold over Nickel | MSL3 [1] | H576 XXXX |

^[1] Max peak reflow temperature of 260 °C

^{[2] 4-}Digit lot number XXXX





SMT GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 18 - 29 GHz OUTPUT

Pin Description

| Pin Number | Function | Description | Interface Schematic |
|------------|------------|--|---------------------|
| 1, 3, 7, 9 | GND | Package bottom must also be connected to RF/DC ground. | GND = |
| 2 | RFIN | Pin is AC coupled and matched to 50 Ohms. | RFIN ○── ├── |
| 4 - 6, 11 | N/C | These pins are internally not connected; however, this product was specified with these pins connected to RF/ DC ground. | |
| 8 | RFOUT | Pin is AC coupled and matched to 50 Ohms. | — —O RFOUT |
| 10, 12 | Vdd2, Vdd1 | Supply voltage 5V \pm 0.5V. External bypass capacitors of 100 pF, 1,000 pF and 2.2 μ F are required. | Vdd1, Vdd2 |

Application Circuit

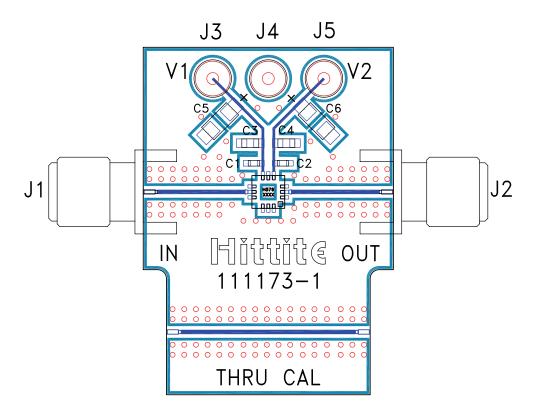
| Component | Value | | | J3 (| $\overline{}$ | | J5 | | | |
|-----------|----------|-----------|----------|---------|---------------|--------------|------|-----|------------|---------------|
| C1, C2 | 100 pF | | | 33 (| | Ĭ | 755 | | | |
| C3, C4 | 1,000 pF | C1 = C | 3 | | | | C2 | C4= | | L |
| C5, C6 | 2.2 μF |] [] [[| 5 工 | I | | | | | | \sqsubseteq |
| | | _ | _ | _ 12 | | | 10 | _ | | _ |
| | | | | Vd | ∟ d1 | Vdo | | | | |
| | | | | | | | | | | |
| | | | _ | | | | | | | |
| | | | <u>2</u> | RFIN | | R | FOUT | 8 | — ○ | |
| | | | J1 | | MC57 | | | | J2 | |
| | | | | " | MC3/ | DLU 3 | 98 | | | |
| | | | | | | | | | | |
| | | | | | | 1,3, | 7.0 | | | |
| | | | | | | 1,3, | 7,3 | | | |
| | | | | | J4 = | _ | | | | |





SMT GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 18 - 29 GHz OUTPUT

Evaluation PCB



List of Materials for Evaluation PCB 112409 [1]

| Item | Description | |
|---------|---------------------------------|--|
| J1, J2 | PCB Mount SRI K Connector | |
| J3 - J5 | DC Pin | |
| C1, C2 | 100 pF Capacitor, 0402 Pkg. | |
| C3, C4 | 1,000 pF Capacitor, 0603 Pkg. | |
| C5, C6 | 2.2 µF Tantalum Capacitor | |
| U1 | HMC576LC3B x2 Active Multiplier | |
| PCB [2] | 111173 Eval Board | |

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for RF Development Tools category:

Click to view products by Analog Devices manufacturer:

Other Similar products are found below:

MAAM-011117 MAAP-015036-DIEEV2 EV1HMC1113LP5 EV1HMC6146BLC5A EV1HMC637ALP5 EVAL-ADG919EBZ ADL5363EVALZ LMV228SDEVAL SKYA21001-EVB SMP1331-085-EVB EV1HMC618ALP3 EVAL01-HMC1041LC4 MAAL-011111-000SMB
MAAM-009633-001SMB 107712-HMC369LP3 107780-HMC322ALP4 SP000416870 EV1HMC470ALP3 EV1HMC520ALC4
EV1HMC244AG16 MAX2614EVKIT# 124694-HMC742ALP5 SC20ASATEA-8GB-STD MAX2837EVKIT+ MAX2612EVKIT#
MAX2692EVKIT# SKY12343-364LF-EVB 108703-HMC452QS16G EV1HMC863ALC4 EV1HMC427ALP3E 119197-HMC658LP2
EV1HMC647ALP6 ADL5725-EVALZ 106815-HMC441LM1 EV1HMC1018ALP4 UXN14M9PE MAX2016EVKIT EV1HMC939ALP4
MAX2410EVKIT MAX2204EVKIT+ EV1HMC8073LP3D SIMSA868-DKL SIMSA868C-DKL SKY65806-636EK1 SKY68020-11EK1
SKY67159-396EK1 SKY66181-11-EK1 SKY65804-696EK1 SKY13396-397LF-EVB SKY13380-350LF-EVB